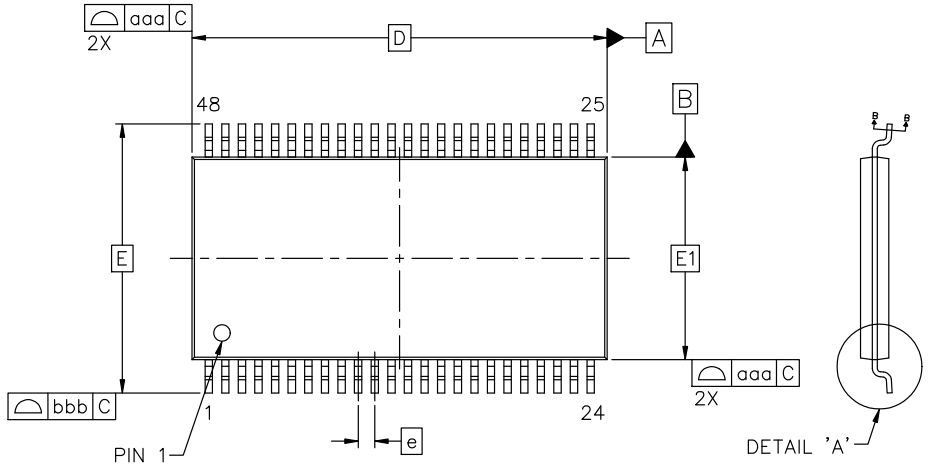
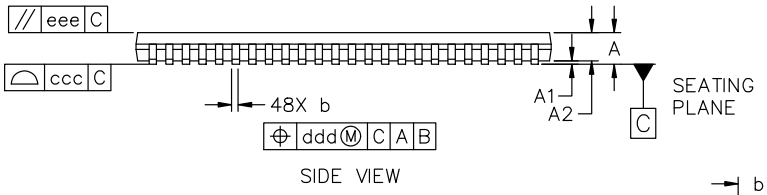
TSSOP−48 12.50x6.10x0.85, 0.50P
CASE 1201−01
ISSUE C

DATE 04 AUG 2026

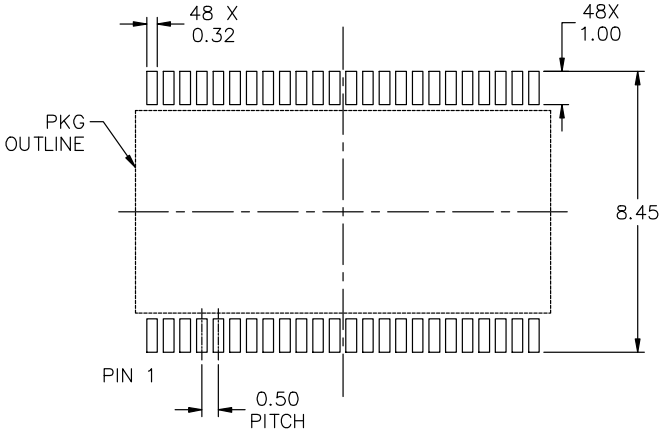
1

SCALE 1:1





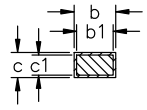
MILLIMETERS			
DIM	MIN	NOM	MAX
A	−−−	−−−	1.10
A1	0.05	0.10	0.15
A2	0.75	0.85	0.95
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
c	0.09	0.15	0.20
c1	0.09	0.12	0.16
D	12.50 BSC		
E	8.10 BSC		
E1	6.10 BSC		
e	0.50 BSC		
L	0.50	0.60	0.70
L1	1.00 REF		
L2	0.25 BSC		
θ	0°	4°	8°
TOLERANCE FORM & POSITION			
aaa	0.10		
bbb	0.20		
ccc	0.10		
ddd	0.13		
eee	0.10		



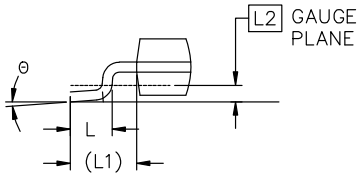
RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb−Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot " ▪", may or may not be present. Some products may not follow the Generic Marking.



DETAIL 'B−B'
SCALE 5:1



DETAIL 'A'
SCALE 2:1

NOTES:
1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.
4. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

GENERIC MARKING DIAGRAM*

XXXXX	= Specific Device Code
A	= Assembly Location
WL	= Wafer Lot
YY	= Year
WW	= Work Week
G	= Pb−Free Package

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DESCRIPTION:	**TSSOP−48 12.50x6.10x0.85, 0.50P**		**PAGE 1 OF 1**

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